

# JLHF150W120R34E6DN

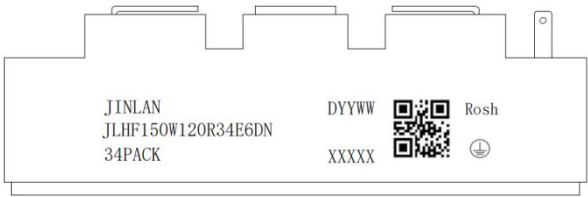
## L34 module with GEN6 IGBT and emitter controlled diode

### Features

- Electrical features
  - $V_{CES} = 1200\text{ V}$
  - $I_{C\text{ nom}} = 150\text{ A} / I_{CRM} = 300\text{ A}$
  - $V_{CESat}$  with positive temperature coefficient
- Mechanical features
  - Standard housing
  - 2.5 kV AC 1 min insulation
  - High creepage and clearance distances
  - Isolated base plate



L34

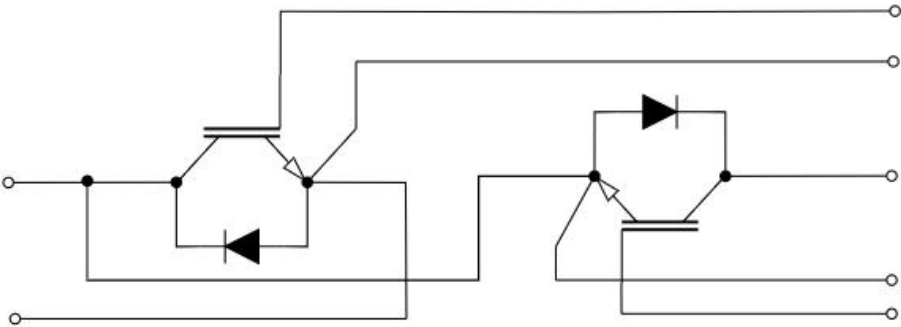


### Typical Applications

- High frequency switching application
- Medical applications
- Motion/servo control
- UPS (Uninterruptible Power Supplies)
- Welding

|                    |                               |
|--------------------|-------------------------------|
| JINLAN             | = Company Name                |
| JLHF150W120R34E6DN | = Specific Device Code        |
| YYWW               | = Year and Work Week Code     |
| XXXXX              | = Serial Number               |
| QR code            | = Custom Assembly Information |

### Description



## Package Insulation coordination

| Symbol      | Parameter                                  | Note or test condition | Values | Unit |
|-------------|--------------------------------------------|------------------------|--------|------|
| $V_{ISOL}$  | Isolation test voltage                     | RMS, f=50Hz, t=60s     | 2.5    | kV   |
| $d_{creep}$ | Creepage distance                          | terminal to heatsink   | 17.0   | mm   |
| $d_{creep}$ | Creepage distance                          | terminal to terminal   | 20.0   | mm   |
| $d_{clear}$ | Clearance                                  | terminal to heatsink   | 17.0   | mm   |
| $d_{clear}$ | Clearance                                  | terminal to terminal   | 9.5    | mm   |
| $CTI$       | Comparative tracking index<br>(electrical) |                        | ≥175   |      |

## Package Characteristic values

| Symbol        | Description                              | Note or test condition                        |           | Values |      |      | Unit |
|---------------|------------------------------------------|-----------------------------------------------|-----------|--------|------|------|------|
|               |                                          |                                               |           | Min.   | Typ. | Max. |      |
| $L_{sCE}$     | Stray Inductance                         |                                               |           | --     | 30   | --   | nH   |
| $R_{CC'+EE'}$ | Module Lead Resistance, Terminal to Chip | $T_C=25^{\circ}C$ , per switch                |           | --     | 0.75 | --   | mΩ   |
| $T_{stg}$     | Storage temperature                      |                                               |           | -40    | --   | 125  | °C   |
| M             | Mounting torque for module mounting      | -Mounting according to valid application note | M5, Screw | 2.5    | --   | 5.0  | Nm   |
| M             | Terminal connection torque               | -Mounting according to valid application note | M6, Screw | 3.0    | --   | 5.0  | Nm   |
| G             | Weight                                   |                                               |           | --     | 155  | --   | g    |

# IGBT

## Absolute Maximum Ratings (T<sub>c</sub> = 25°C unless otherwise noted)

| Symbol           | Description                                                                      | Note or test condition                             | Value | Unit |
|------------------|----------------------------------------------------------------------------------|----------------------------------------------------|-------|------|
| V <sub>CES</sub> | Collector-Emitter Voltage                                                        | T <sub>vj</sub> = 25 °C                            | 1200  | V    |
| I <sub>CDC</sub> | Continuous Collector Current @ T <sub>c</sub> = 80°C (T <sub>JMAX</sub> = 175°C) |                                                    | 150   | A    |
| I <sub>CRM</sub> | Repetitive peak collector current                                                | Peak Collector Current@ tp=1ms                     | 300   | A    |
| P <sub>tot</sub> | Total power dissipation                                                          | T <sub>c</sub> = 25°C, T <sub>vj max</sub> = 150°C | 568   | W    |
| V <sub>GES</sub> | Gate-emitter peak voltage                                                        |                                                    | ±30   | V    |

## Characteristics (T<sub>c</sub> = 25°C unless otherwise noted)

| Symbol               | Parameter                            | Test Condition                                                                                                      |                       | Rating |      |     | Unit |
|----------------------|--------------------------------------|---------------------------------------------------------------------------------------------------------------------|-----------------------|--------|------|-----|------|
|                      |                                      |                                                                                                                     |                       | Min    | Typ  | Max |      |
| V <sub>CE(sat)</sub> | Collector-Emitter Saturation Voltage | I <sub>C</sub> =150A<br>V <sub>GE</sub> =15V                                                                        | T <sub>j</sub> =25°C  | --     | 2.0  | 2.8 | V    |
|                      |                                      |                                                                                                                     | T <sub>j</sub> =150°C | --     | 2.4  | --  |      |
| V <sub>GE(TH)</sub>  | Gate-Emitter Threshold Voltage       | I <sub>C</sub> =3mA, V <sub>CE</sub> =V <sub>GE</sub> , T <sub>vj</sub> = 25°C                                      |                       | 4.5    | --   | 6.5 | V    |
| I <sub>CES</sub>     | Collector-Emitter Cutoff Current     | V <sub>GE</sub> =0V, V <sub>CE</sub> =1200V, T <sub>vj</sub> = 25°C                                                 |                       | --     | --   | 1   | mA   |
| I <sub>GES</sub>     | Gate-Emitter Leakage Current         | V <sub>GE</sub> = ±20V , V <sub>CE</sub> = 0 V , T <sub>vj</sub> = 25°C                                             |                       | --     | --   | 100 | nA   |
| R <sub>Gint</sub>    | Internal Gate Resistance             | T <sub>vj</sub> = 25 °C                                                                                             |                       | --     | 0.8  | --  | Ω    |
| C <sub>ies</sub>     | Input Capacitance                    | V <sub>CE</sub> =30V, V <sub>GE</sub> =0V, f=1MHz, T <sub>vj</sub> = 25°C                                           |                       | --     | 28.2 | --  | nF   |
| C <sub>oes</sub>     | Output Capacitance                   |                                                                                                                     |                       | --     | 0.63 | --  |      |
| C <sub>res</sub>     | Reverse Transfer Capacitance         |                                                                                                                     |                       | --     | 0.62 | --  |      |
| Q <sub>g</sub>       | Total Gate Charge                    | V <sub>CC</sub> =960V, I <sub>C</sub> =150A,<br>V <sub>GE</sub> =15V, T <sub>vj</sub> = 25°C                        |                       | --     | 0.89 | --  | uC   |
| Q <sub>ge</sub>      | Gate to Emitter Charge               |                                                                                                                     |                       | --     | 0.16 | --  |      |
| Q <sub>gc</sub>      | Gate to Collector Charge             |                                                                                                                     |                       | --     | 0.42 | --  |      |
| t <sub>d(ON)</sub>   | Turn-on Delay Time                   | V <sub>CE</sub> =600V, I <sub>C</sub> =150A,<br>V <sub>GE</sub> =15/-5V, R <sub>g</sub> =7.8Ω<br><br>Inductive Load |                       | --     | 19   | --  | ns   |
| t <sub>r</sub>       | Rise Time                            |                                                                                                                     |                       | --     | 25   | --  |      |
| t <sub>d(OFF)</sub>  | Turn-Off Delay Time                  |                                                                                                                     |                       | --     | 313  | --  |      |
| t <sub>f</sub>       | Fall Time                            |                                                                                                                     |                       | --     | 15   | --  |      |
| E <sub>on</sub>      | Turn-On Switching Loss               |                                                                                                                     |                       | --     | 19.2 | --  | mJ   |
| E <sub>off</sub>     | Turn-Off Switching Loss              |                                                                                                                     |                       | --     | 6.9  | --  |      |
| E <sub>ts</sub>      | Total Switching Loss                 |                                                                                                                     |                       | --     | 25.1 | --  |      |

|              |                                        |          |     |     |                   |     |
|--------------|----------------------------------------|----------|-----|-----|-------------------|-----|
| $R_{thJC}$   | Thermal resistance, junction to case   | per IGBT | --  | 0.2 | --                | K/W |
| $T_{vj\ op}$ | Temperature under switching conditions |          | -40 | --  | 150 <sup>1)</sup> | °C  |

<sup>1)</sup> $T_{vj\ op} > 150^{\circ}\text{C}$  is only allowed for operation at overload conditions. For detailed specifications please refer to AN 2018-14.

## Diode

### Absolute Maximum Ratings ( $T_c = 25^{\circ}\text{C}$ unless otherwise noted)

| Symbol    | Description                     | Note or test condition        | Value | Unit |
|-----------|---------------------------------|-------------------------------|-------|------|
| $V_{RRM}$ | Repetitive peak reverse voltage | $T_{vj} = 25^{\circ}\text{C}$ | 1200  | V    |
| $I_F$     | Continuous DC forward current   |                               | 150   | A    |
| $I_{FRM}$ | Repetitive peak forward current | $t_P = 1\ \text{ms}$          | 300   | A    |

### Characteristics ( $T_c = 25^{\circ}\text{C}$ unless otherwise noted)

| Symbol       | Parameter                              | Test Conditions                                                                             | Rating |      |                   | Units         |
|--------------|----------------------------------------|---------------------------------------------------------------------------------------------|--------|------|-------------------|---------------|
|              |                                        |                                                                                             | Min.   | Typ. | Max.              |               |
| $V_F$        | Diode Forward Voltage                  | $I_F = 150\text{A}$                                                                         | --     | 3.3  | 4.2               | V             |
| $T_{rr}$     | Reverse Recovery Time                  | $V_{CE} = 600\text{V}, I_F = 150\text{A},$<br>$V_{GE} = 15/-5\text{V}$<br>$R_g = 7.8\Omega$ | --     | 260  | --                | ns            |
| $I_{RRM}$    | Diode Peak Reverse Recovery Current    |                                                                                             | --     | 35   | --                | A             |
| $Q_{rr}$     | Reverse Recovery Charge                |                                                                                             | --     | 2.8  | --                | $\mu\text{C}$ |
| $E_{rec}$    | Reverse Recovery Energy                |                                                                                             | --     | 2.3  | --                | mJ            |
| $R_{thJC}$   | Thermal resistance, junction to case   | per Diode                                                                                   | --     | 0.45 | --                | K/W           |
| $T_{vj\ op}$ | Temperature under switching conditions |                                                                                             | -40    | --   | 150 <sup>2)</sup> | °C            |

<sup>2)</sup> $T_{vj\ op} > 150^{\circ}\text{C}$  is only allowed for operation at overload conditions. For detailed specifications please refer to AN 2018-14.

Typical Electrical and Thermal Characteristics

Figure 1 Output Characteristics

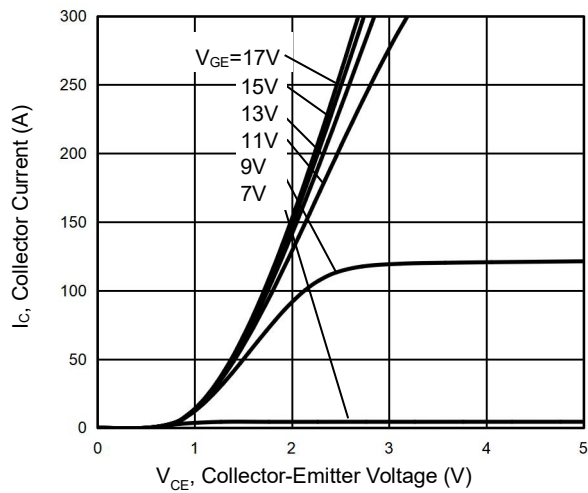


Figure 2 Transfer Characteristics

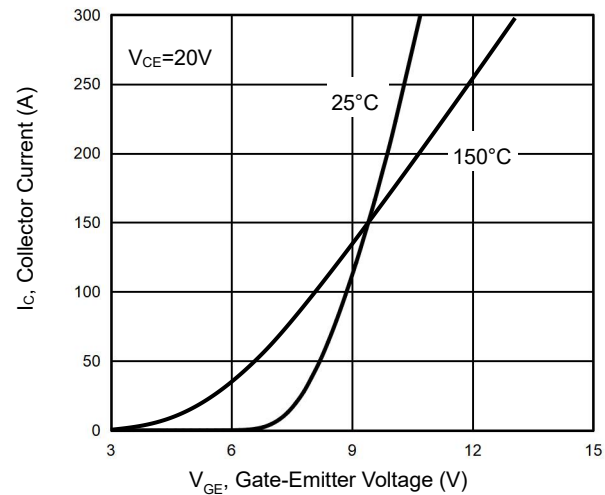


Figure 3  $V_{CE(sat)}$  vs. Case Temperature

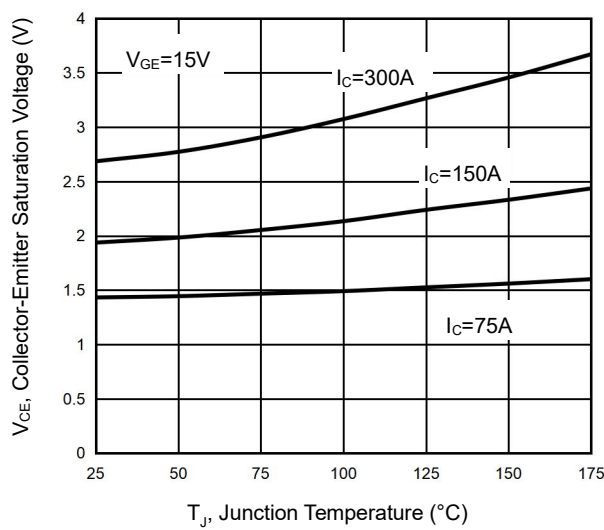


Figure 4 Saturation Voltage vs.  $V_{GE}$

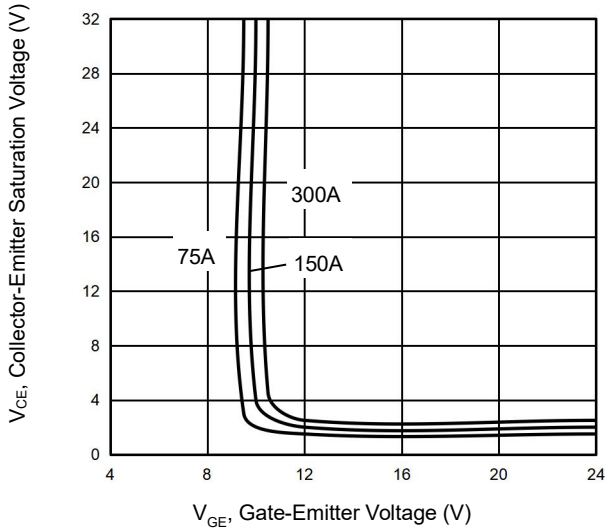


Figure 5 Capacitance Characteristics

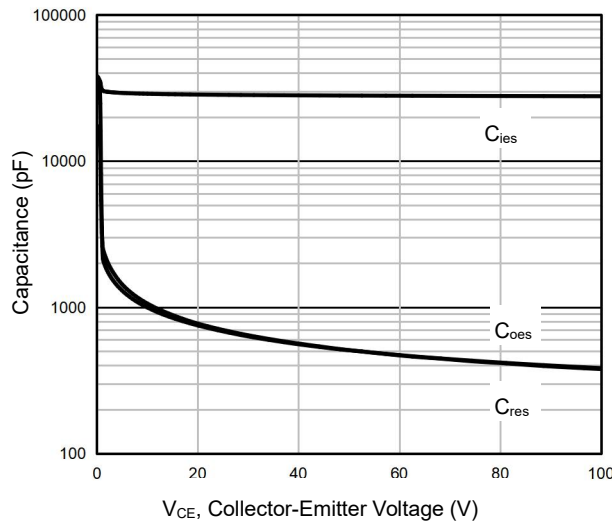
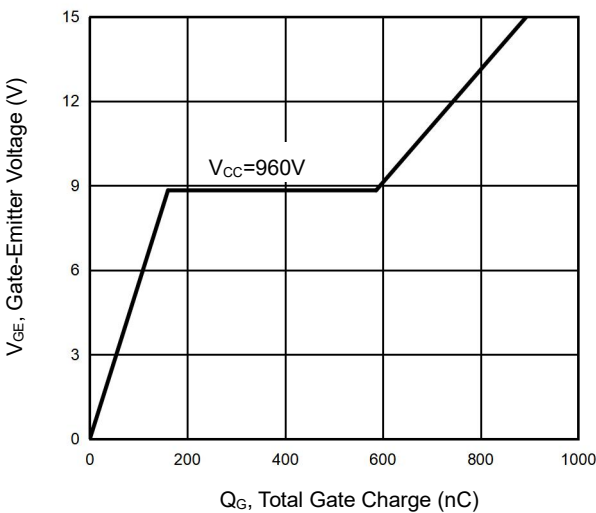


Figure 6 Gate Charge Waveform





## Typical Electrical and Thermal Characteristics

Figure 7 Forward Characteristics

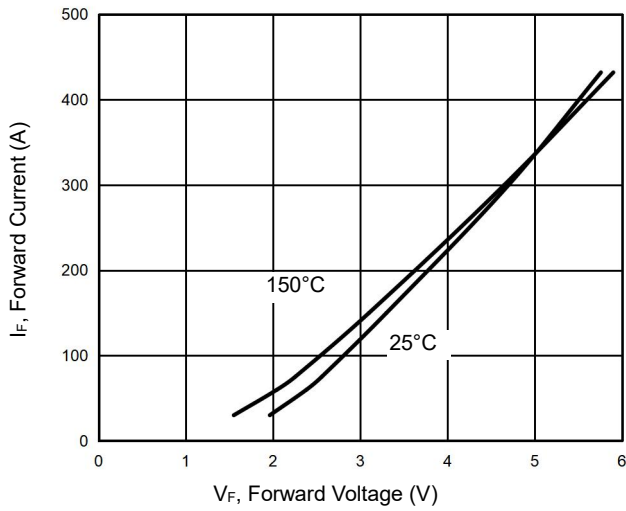


Figure 8  $V_F$  vs. Temperature

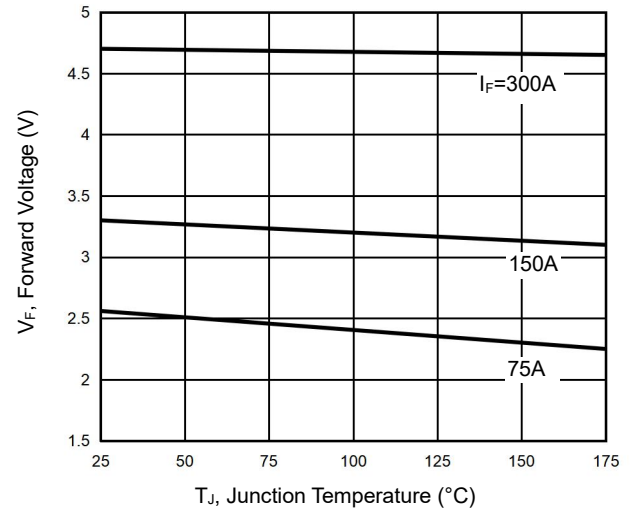


Figure 9 Gate-emitter Threshold Voltage as a Function of Junction Temperature

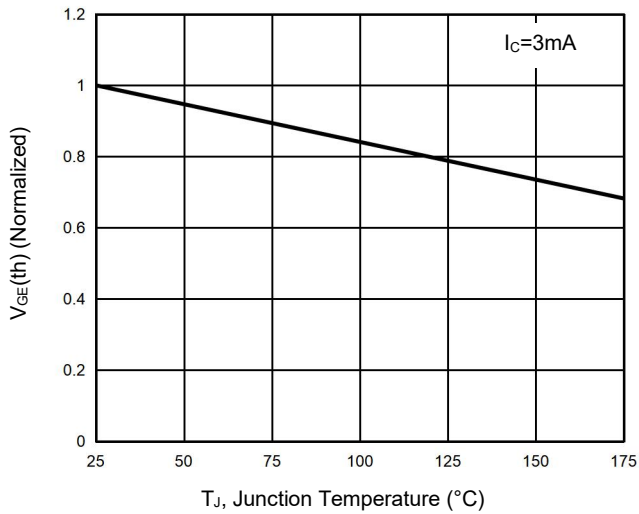
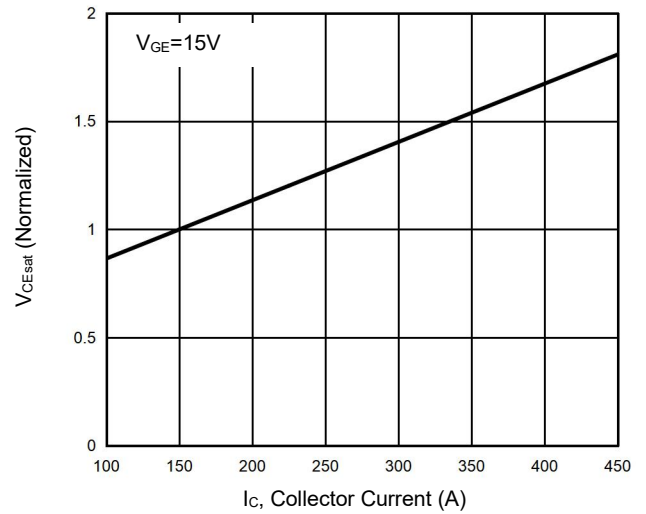
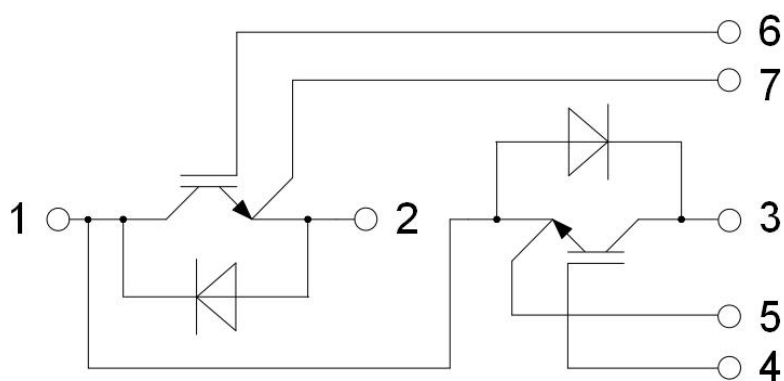


Figure 10 Typical Collector-emitter Saturation Voltage as a function of Collector Current



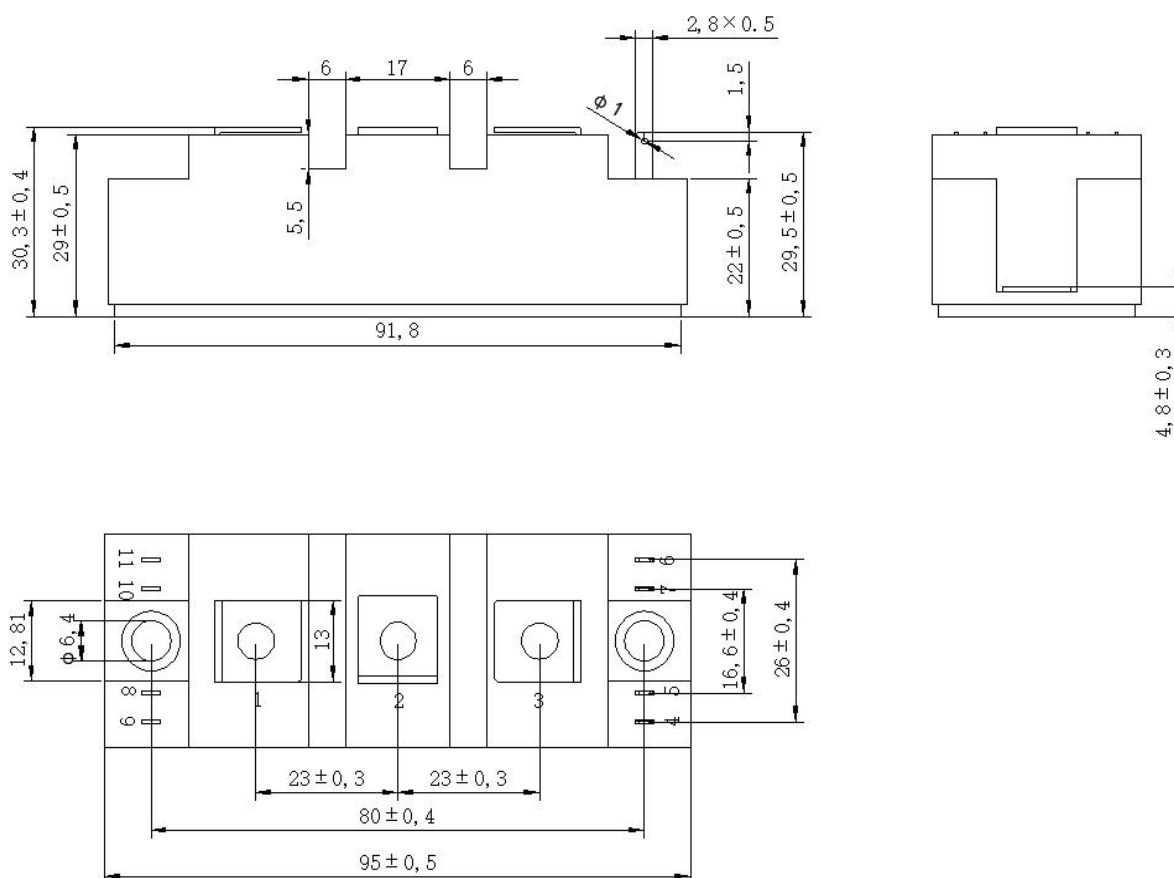


## Circuit Diagram



## Package Dimensions

Dimensions in Millimeters



**REVISION HISTORY**

| Document version | Date of release | Description of changes |
|------------------|-----------------|------------------------|
| Rev.00           | 2024-08-06      | Preview                |
|                  |                 |                        |

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